



Preliminary Product Information Sheet

(Note: These are typical properties to be used as a guide only, not a specification. Data below is not guaranteed. Different batches, conditions and applications yield differing results.)

MATERIAL ID: EPO-TEK® T6116-1 (formerly 93-87-1)

Date: May 2013

Rev: I

Material Description: A single component, thermally conductive and electrically insulating die attach epoxy for in-line snap cure and JEDEC level semiconductor packaging. It can be used with many types of IC's and lead frames, and has versatility in cure either by traditional box oven means or snap cure on a wire bonding hot plate chuck. It is the replacement for EPO-TEK® T6116.

Number of Components: Single

Mix Ratio by Weight: N/A

Recommended Cure: 150°C/1 Hour

Specific Gravity: 1.46

Pot Life: 7 Days

Shelf Life: One year at -40°C

Minimum Alternative Cure(s):
may not achieve performance properties below:
200°C / 1 Minute
175°C / 5 Minutes

NOTE: Container(s) should be kept closed when not in use. Filled systems should be stirred thoroughly before mixing and prior to use.

MATERIAL CHARACTERISTICS:

PHYSICAL PROPERTIES:

Color (before cure):	Light yellow
Consistency	Smooth paste
Viscosity (23°C): @ 10 rpm	20,830 cPs
Thixotropic Index:	1.9
Glass Transition Temp:	102 °C
Coefficient of Thermal Expansion (CTE):	
Below Tg:	46 x 10 ⁻⁶ in/in°C
Above Tg:	131 x 10 ⁻⁶ in/in°C
Shore D Hardness:	70
Die Shear @ 23°C:	27 Kg
Degradation Temp:	408 °C
Weight Loss:	
@ 200°C	< 0.05 %
@ 250°C	0.13 %
@ 300°C	0.35 %
Operating Temp:	
Continuous:	- 55°C to 250°C
Intermittent:	- 55°C to 350°C
Storage Modulus:	534,999 psi
Particle Size:	≤ 20 microns

ELECTRICAL AND THERMAL PROPERTIES:

Thermal Conductivity: 0.48 W/mK

The data above is INITIAL only - it may be changed at anytime, for any reason without notice to anyone. It is provided only as a guide for evaluation/consideration.

*These material characteristics are typical properties that are based on a limited number of samples/batches. All properties are based on the cure indicated above. Some properties may vary as manufactured quantities are scaled up to commercialized production levels.